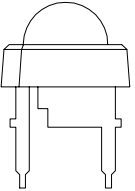


Features:

- Three dice - Tri-colour
- Water clear epoxy
- Low thermal resistance copper leadframe
- 4 leads with stand off
- Class II ESD Rating

Electro / Optical Characteristics $I_F = 20 \text{ mA}$ $T_a = 25^\circ \text{ C}$

LED Lamp Package	LED Part Number	Emitting Colour	Epoxy Type	Die Material	Wavelength		Forward Voltage V_F		Luminous intensity I_V		Viewing \angle $2\theta^{1/2}$
					Peak λ_p	Dominant λ_d	typical	max	min	typical	
 7.6 x 7.6 mm	FCL-P5DR078G03B12WCCI	Red	WC	AlGaInP	632	624	2.00	2.40	-	400	65
		Green		InGaN/SiC	518	525	3.70	4.20	-	400	
		Blue		InGaN/SiC	468	470	3.75	4.00	-	260	
	Units				nm		V		mcd		deg

Maximum Ratings per die $T_a = 25^\circ \text{ C}$ (Derate above 25° C)

Characteristic	Condition	Symbol	Rating
Pulse Forward Current	0.1 duty cycle @ 1KHz	I_{FP}	100
DC Forward Current		I_F	50
Reverse Voltage	$I_R = 10 \mu\text{A}$	V_R	10
Pulse Forward Current	0.1 duty cycle @ 1KHz	I_{FP}	100
DC Forward Current		I_F	35
Reverse Voltage	$I_R = 10 \mu\text{A}$	V_R	5
Operating Temperature		T_{opr}	- 20 to + 80
Storage Temperature		T_{stg}	- 20 to + 100
Lead soldering temperature	1.6 mm from body - max. 3 seconds		240

Note

Consideration must be given to forward current levels at elevated temperatures when driving all dice simultaneously to ensure maximum efficiency over the life of the product.

Industry standard procedures regarding static must be observed when handling product produced with the following die material.

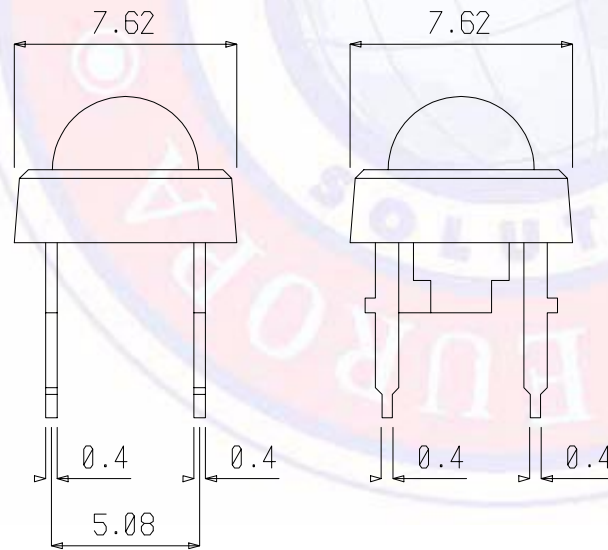
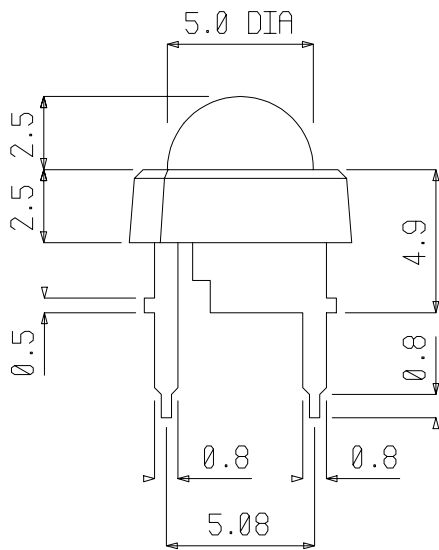
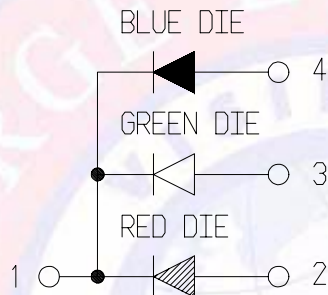
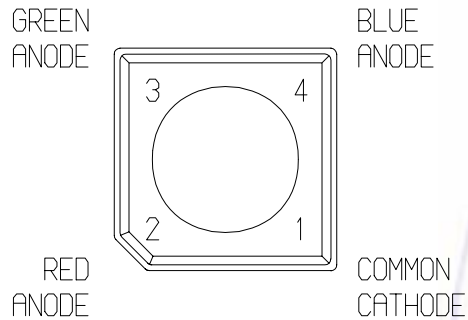
InGaN/SiC

It is the responsibility of the customer to verify the suitability of the product for the application.

Package Outline

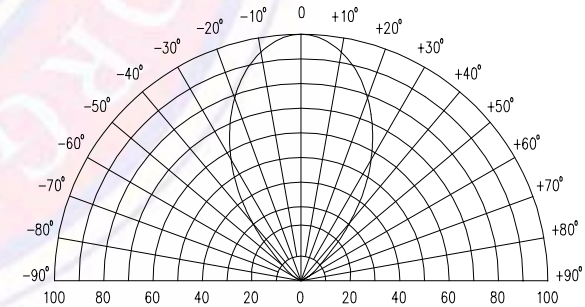
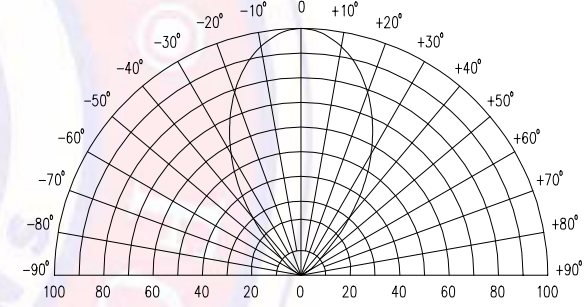
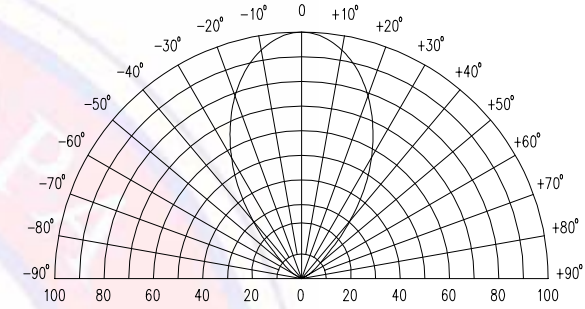
Dimensions in mm

Tol ± 0.25 mm unless stated



Radiation Diagrams

$T_a = 25^\circ\text{C}$



Relative angular intensity

Note:

Due to manufacturing tolerances the maximum intensity position may deviate from the 0° point.